P/P system



CCD inspection



Vacuum suction



Handler operating interface



Inspection operating interface



CLASSIFICATION SYSTEM CF-S750

Automatic disassemble / batch system of JEDEC Tray

It is equipped with a CCD inspection system to avoid abnormal mixing and printing quality.

Support multiple output modes (sweep/batch/disassemble), which can be selected according to the production line.

Automatic Loading and unloading module

Able to load 25 trays, also can replenish products in dynamics.

The sweep mode

Can check the overall product quality.

The disassemble mode

In addition to the quality control, it can also control the shipment quantity.

The batch mode

It can control the shipment quantity of per batch and total quantity.

The CCD inspection adopts the Vitrox® vision system

The basic marking is checked in loading area, and the basic lead and direction are checked in unloading area.

CCD light source system

Can be used for inspection of ink or laser mark.

After the good products are arrayed

According to normal products, transferred to the unloading area.

Barcode Reader (optional)

Imports data to network connection systems automatically.

High-speed P/P module

3 suctions can adjust mechanism automatically for replenishing and sorting products.

No need to modify the machine

It only needs to select the work file to produce, no need to modify the machine. *

* "No need to modify the machine" means that the hardware does not need to change with different work but does not include the suctions replacement when the product size is different..



Items	Specification Descriptions
Machine Dimension	2160(W) x 1490(D) x 2150(H) mm
Machine Weight	1200 kg
U. P. H.	(Just One last tray in the LOT and NO units rejected or any abnormal system stop.) Scan/Split Mode: > 15K Merge Mode: > 10K *For above U.P.H. calculation not included operate preparation time.
Facility Consumption	200~240V; 1ø3W; 50/60Hz; 25A
Air supply	5 kgf/cm², AVG 30L/min
Conversion Time	< 10 mins
Application Tray Type	Standard JEDEC Tray
Application Package Type/Size	TSOP / QFP / QFN / BGA / CSP on 3x3 to 40x40